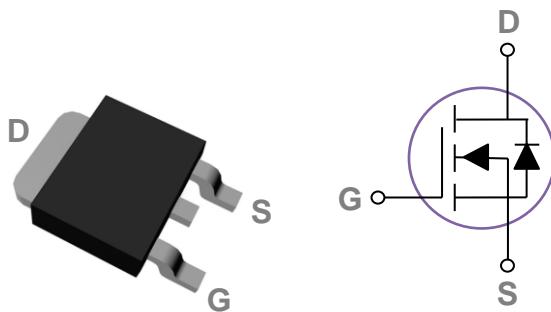


### General Description

These N-Channel enhancement mode power field effect transistors are using super junction MOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

### TO252 Pin Configuration



BVDSS	RDS(ON)	ID
650V	900mΩ	5A

### Features

- 650V,5A,  $RDS(ON) = 900m\Omega @ VGS = 10V$
- Improved dv/dt capability
- Fast switching
- 100% EAS Guaranteed
- Green Device Available

### Applications

- PFC Power Supply Stages
- Motor Control
- DC-DC Converters
- Adapter

### Absolute Maximum Ratings $T_c=25^\circ C$ unless otherwise noted

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	650	V
$V_{GS}$	Gate-Source Voltage	$\pm 30$	V
$I_D$	Drain Current – Continuous ( $T_c=25^\circ C$ )	5	A
	Drain Current – Continuous ( $T_c=100^\circ C$ )	3.2	A
$I_{DM}$	Drain Current – Pulsed <sup>1</sup>	20	A
EAS	Single Pulse Avalanche Energy	46	mJ
$P_D$	Power Dissipation ( $T_c=25^\circ C$ )	45	W
	Power Dissipation – Derate above 25°C	0.36	W/°C
$T_{STG}$	Storage Temperature Range	-55 to 150	°C
$T_J$	Operating Junction Temperature Range	-55 to 150	°C

### Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction to ambient	---	62	°C/W
$R_{\theta JC}$	Thermal Resistance Junction to Case	---	2.8	°C/W



650V N-Channel MOSFETs

PJD05N65N

**Electrical Characteristics ( $T_J=25\text{ }^{\circ}\text{C}$ , unless otherwise noted)****Off Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$ , $I_D=1\text{mA}$	650	---	---	V
$I_{DSS}$	Drain-Source Leakage Current	$V_{DS}=650\text{V}$ , $V_{GS}=0\text{V}$ , $T_J=25\text{ }^{\circ}\text{C}$	---	---	1	uA
		$V_{DS}=520\text{V}$ , $V_{GS}=0\text{V}$ , $T_J=125\text{ }^{\circ}\text{C}$	---	---	10	uA
$I_{GSS}$	Gate-Source Leakage Current	$V_{GS}=\pm 30\text{V}$ , $V_{DS}=0\text{V}$	---	---	$\pm 100$	nA

**On Characteristics**

$R_{DS(\text{ON})}$	Static Drain-Source On-Resistance	$V_{GS}=10\text{V}$ , $I_D=1.5\text{A}$	---	760	900	$\text{m}\Omega$
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{GS}=V_{DS}$ , $I_D = 250\text{uA}$	2	3	4	V

**Dynamic and switching Characteristics**

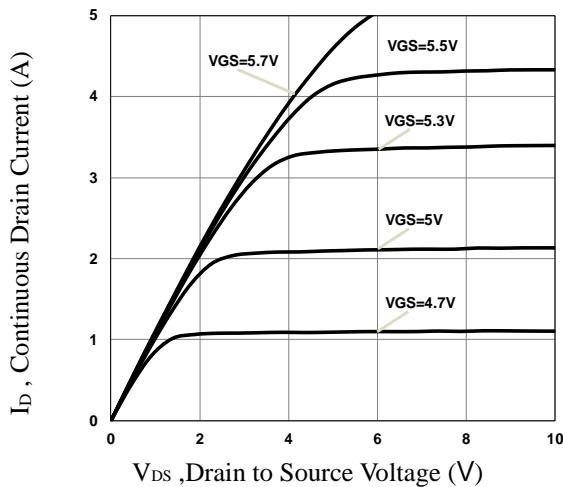
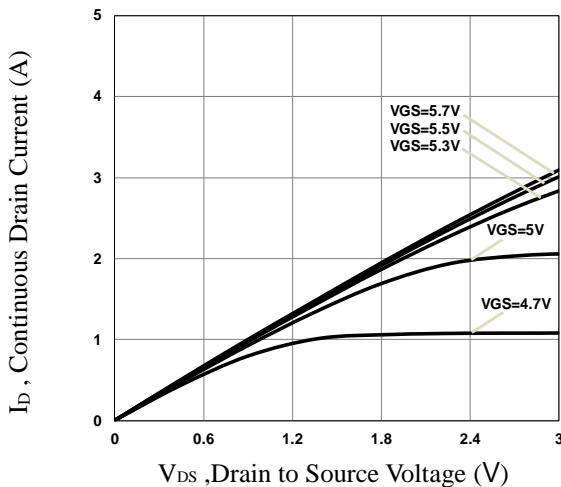
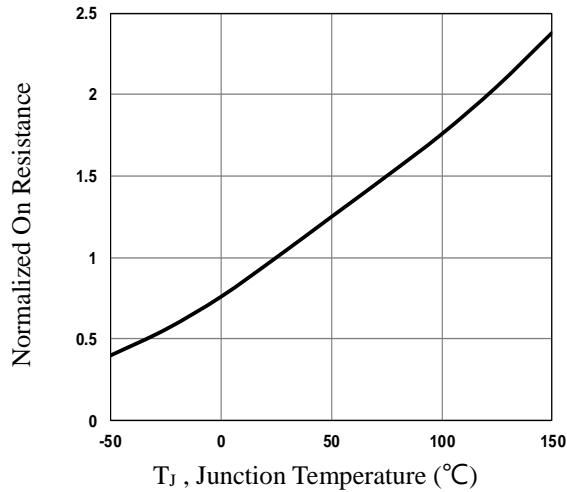
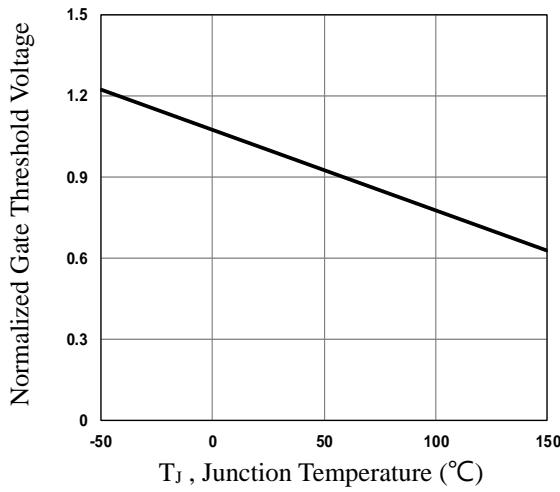
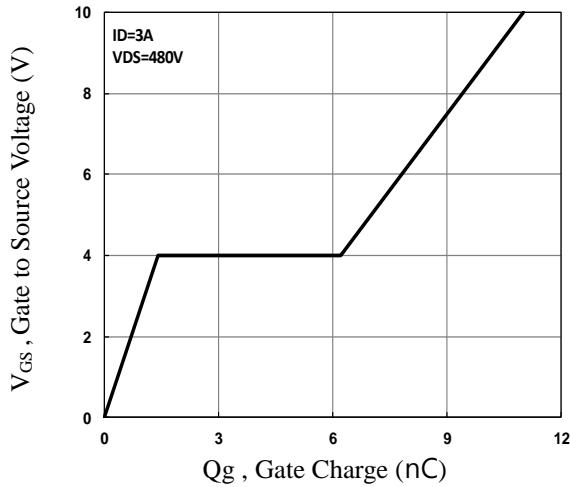
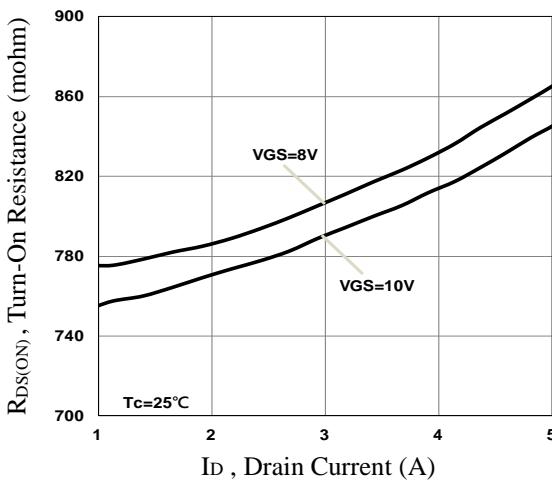
$Q_g$	Total Gate Charge <sup>2,3</sup>	$V_{DS}=480\text{V}$ , $V_{GS}=10\text{V}$ , $I_D=3\text{A}$	---	11	17	nC
$Q_{gs}$	Gate-Source Charge <sup>2,3</sup>		---	1.4	5	
$Q_{gd}$	Gate-Drain Charge <sup>2,3</sup>		---	4.8	8	
$T_{d(on)}$	Turn-On Delay Time <sup>2,3</sup>	$V_{DS}=480\text{V}$ , $V_{GS}=10\text{V}$ , $R_G=25\Omega$ $I_D=3\text{A}$	---	14	21	ns
$T_r$	Rise Time <sup>2,3</sup>		---	25	40	
$T_{d(off)}$	Turn-Off Delay Time <sup>2,3</sup>		---	45	70	
$T_f$	Fall Time <sup>2,3</sup>		---	20	30	
$C_{iss}$	Input Capacitance	$V_{DS}=100\text{V}$ , $V_{GS}=0\text{V}$ , $F=1\text{MHz}$	---	335	505	pF
$C_{oss}$	Output Capacitance		---	17	26	
$C_{rss}$	Reverse Transfer Capacitance		---	1	4	

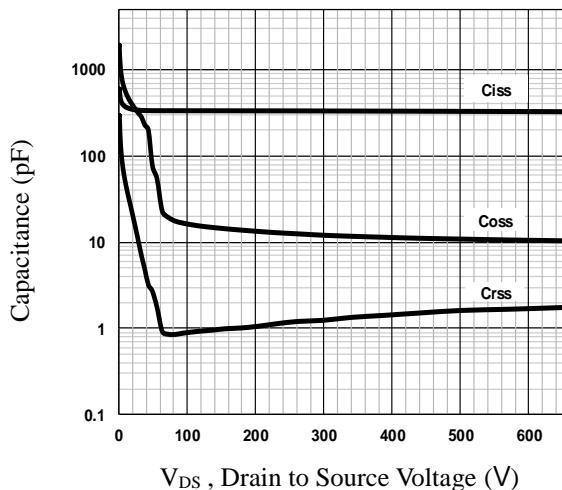
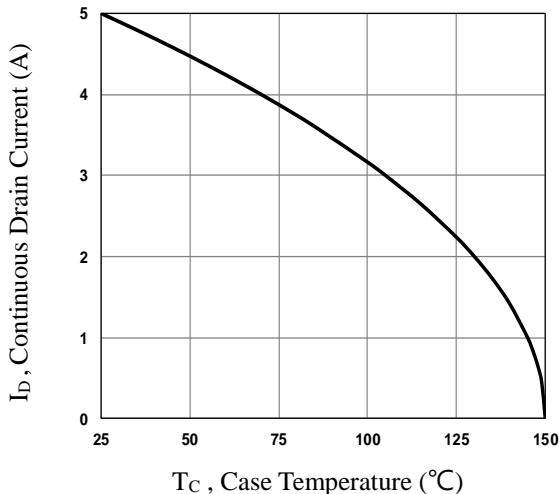
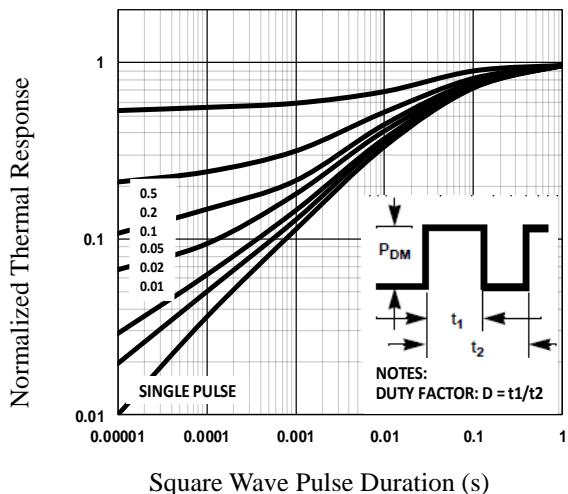
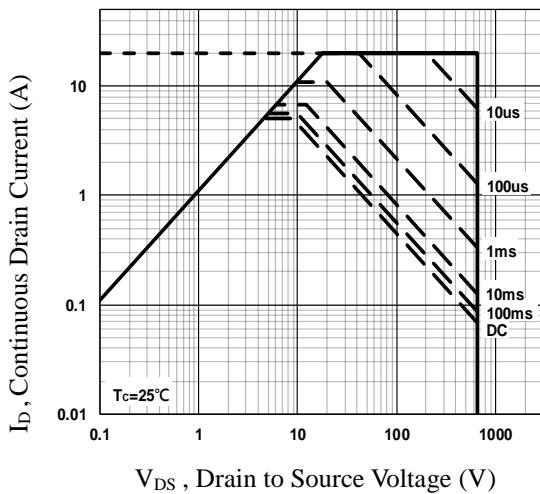
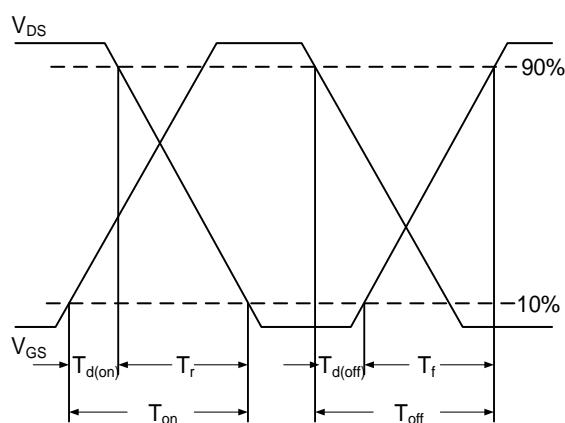
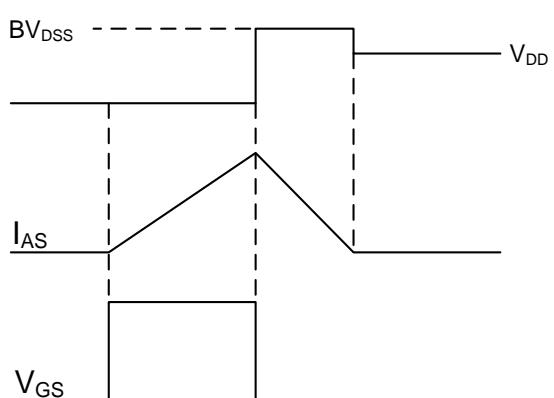
**Drain-Source Diode Characteristics and Maximum Ratings**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_s$	Continuous Source Current	$V_G=V_D=0\text{V}$ , Force Current	---	---	5	A
$I_{SM}$	Pulsed Source Current		---	---	10	A
$V_{SD}$	Diode Forward Voltage	$V_{GS}=0\text{V}$ , $I_s=3\text{A}$ , $T_J=25\text{ }^{\circ}\text{C}$	---	---	1.4	V
$t_{rr}$	Reverse Recovery Time	$V_R=400\text{V}$ , $I_s=3\text{A}$ $di/dt=100\text{A}/\mu\text{s}$ , $T_J=25\text{ }^{\circ}\text{C}$	---	240	---	ns
$Q_{rr}$	Reverse Recovery Charge		---	1.9	---	uC

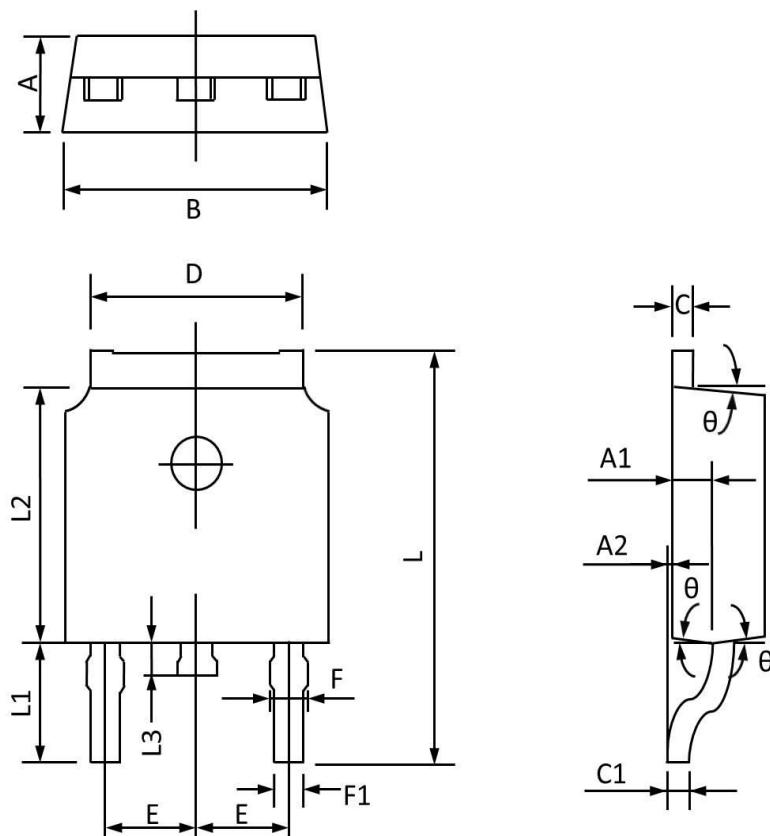
Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed , pulse width  $\leq 300\text{us}$  , duty cycle  $\leq 2\%$ .
3. Essentially independent of operating temperature.


**Fig.1 Typical Output Characteristics**

**Fig.2 Typical Output Characteristics**

**Fig.3 Normalized RDSON vs.  $T_J$** 

**Fig.4 Normalized  $V_{th}$  vs.  $T_J$** 

**Fig.5 Gate Charge Characteristics**

**Fig.6 Turn-On Resistance vs.  $I_D$**


**Fig.7 Capacitance Characteristics**

**Fig.8 Continuous Drain Current vs.  $T_c$** 

**Fig.9 Normalized Transient Impedance**

**Fig.10 Maximum Safe Operation Area**

**Fig.11 Switching Time Waveform**

**Fig.12 EAS Waveform**

## TO252 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	2.450	2.150	0.096	0.085
A1	1.200	0.910	0.047	0.036
A2	0.150	0.000	0.006	0.000
B	6.800	6.300	0.268	0.248
C	0.580	0.350	0.023	0.014
C1	0.550	0.380	0.022	0.015
D	5.500	5.100	0.217	0.201
E	2.390	2.000	0.094	0.079
F	0.940	0.600	0.037	0.024
F1	0.860	0.500	0.034	0.020
L	10.400	9.400	0.409	0.370
L1	3.000	2.400	0.118	0.094
L2	6.200	5.300	0.244	0.209
L3	1.200	0.600	0.047	0.024
θ	9°	3°	9°	3°